



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE4963-2M			<b>Issued</b>	24. August 2015			
<b>MA#</b>	MA001106126							
<b>Package</b>	PG-SOT23-3-15			<b>Weight*</b>	9.78 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.220	2.25	2.25	22463	22463
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		74	
	non noble metal	titanium	7440-32-6	0.004	0.04		369	
	non noble metal	chromium	7440-47-3	0.011	0.11		1106	
wire	non noble metal	copper	7440-50-8	3.590	36.72	36.88	367219	368768
	noble metal	gold	7440-57-5	0.023	0.24	0.24	2355	2355
	encapsulation	organic material	carbon black	1333-86-4	0.055	0.56		5619
encapsulation	plastics	epoxy resin	-	1.181	12.08		120813	
	inorganic material	silicondioxide	60676-86-0	4.257	43.55	56.19	435491	561923
leadfinish	non noble metal	tin	7440-31-5	0.150	1.53	1.53	15308	15308
plating	noble metal	silver	7440-22-4	0.149	1.52	1.52	15200	15200
glue	plastics	epoxy resin	-	0.024	0.24		2447	
	noble metal	silver	7440-22-4	0.113	1.15	1.39	11536	13983
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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